

ABSTRACT

A method and a device for placing a multitude of shaped parts of solder material (20) on a bond pad arrangement (29) of a substrate (23), said bond pad arrangement comprising a multitude of bond pads (28), and for subsequent re-melting of the shaped parts of solder material on the bond pads (28), with arrangement of a template device (21) comprising a multitude of template apertures (27) for accommodating shaped parts of solder material (20) opposite a substrate (23) comprising a bond pad arrangement (29), such that the shaped parts of solder material are associated with the individual bond pads (28); and application of laser energy to the shaped parts of solder material (20) accommodated in the template apertures (27) using a laser device (39) arranged at the rear of the template device (21) such that said laser energy is applied to the shaped parts of solder material through the template device.

(Fig. 1)